## FUĴĨTSU

# PRIMERGY RX300 S8

### System configurator and order-information guide

#### June 2014



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Change report



#### **PRIMERGY Server**

#### Instructions

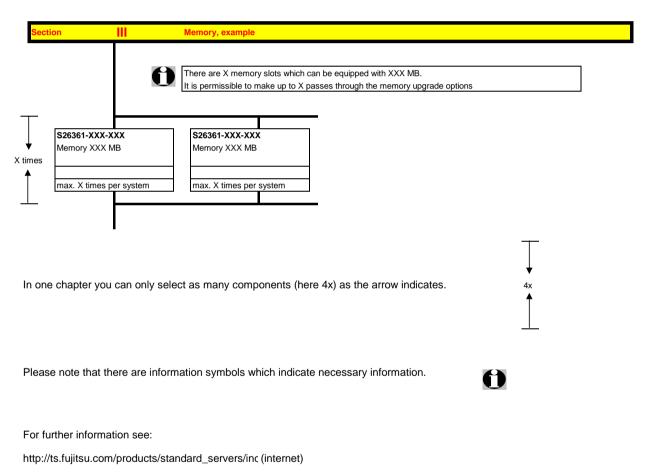
This document contains basic product and configuration information that will enable you to configure your system via PC-/System-Architect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.

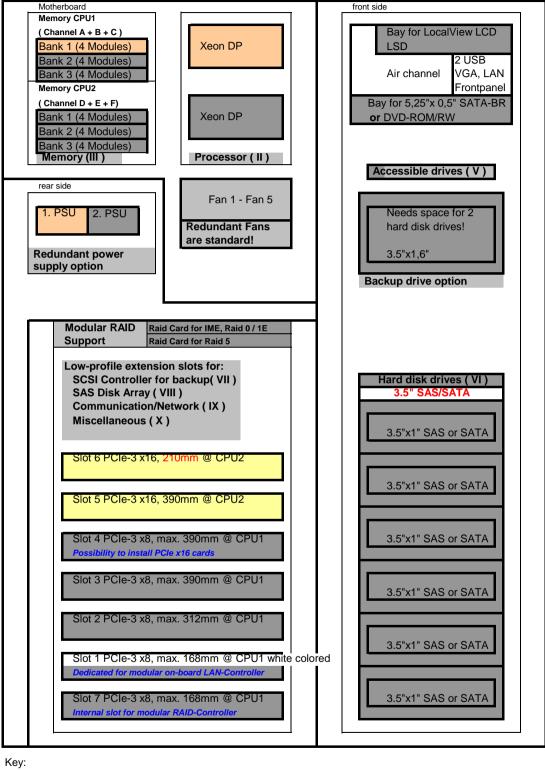


https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy\_config/current/Pages/default.aspx (extranet)

#### **Configuration diagram PRIMERGY RX300 S8**

#### System unit (I)

with up to 6x 3.5" Hard disk drives



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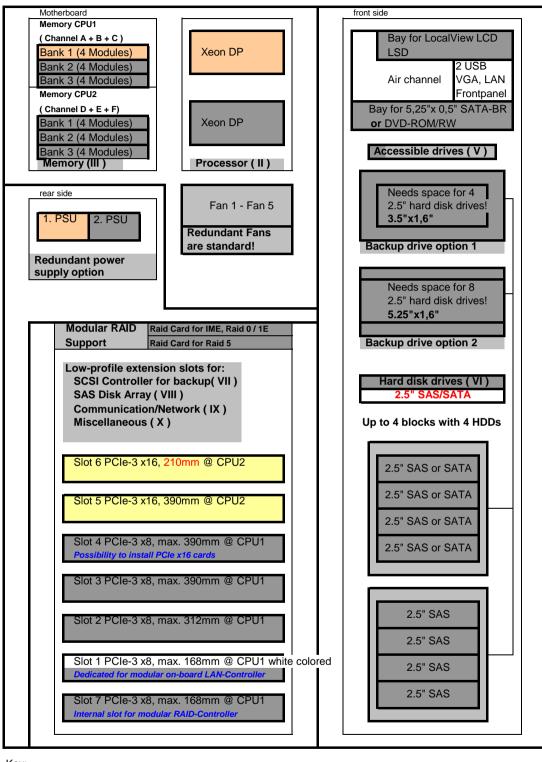
Included in basic unit

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Option

#### Configuration diagram PRIMERGY RX300 S8

#### System unit (I)



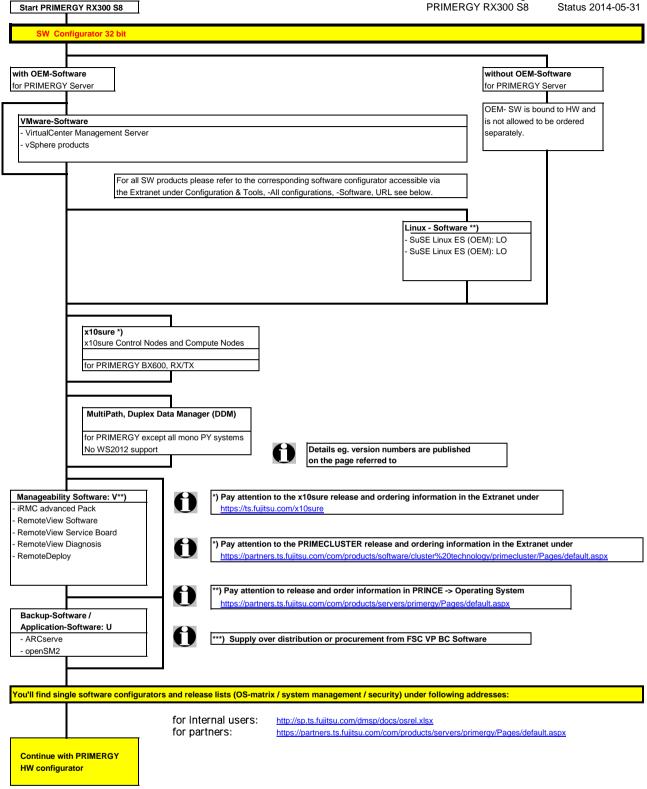
with up to 4, 8, 12 or 16x 2.5" Hard disk drives or up to 4 or 8 PCIe SSDs 2.5"

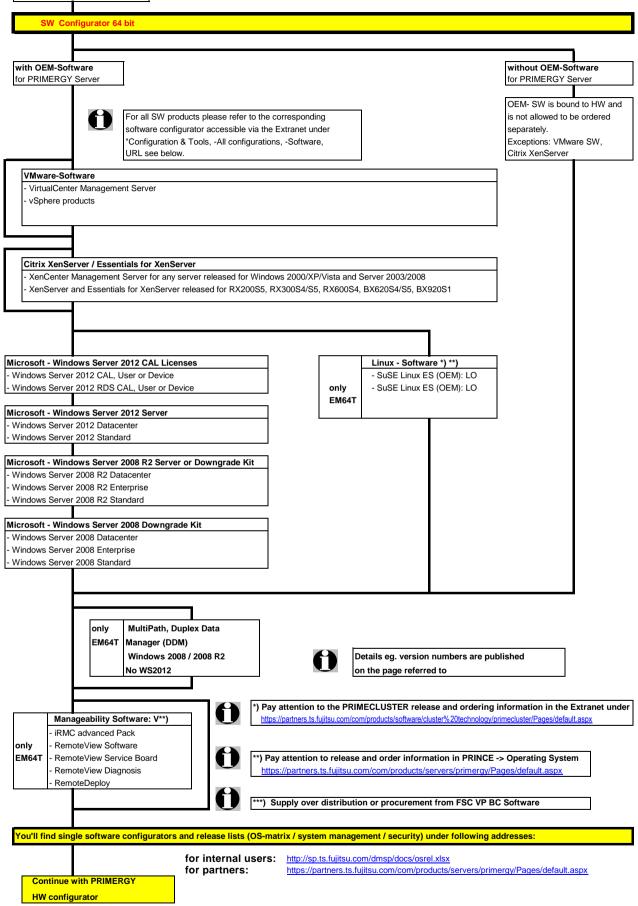
Key:

Included in basic unit

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Option

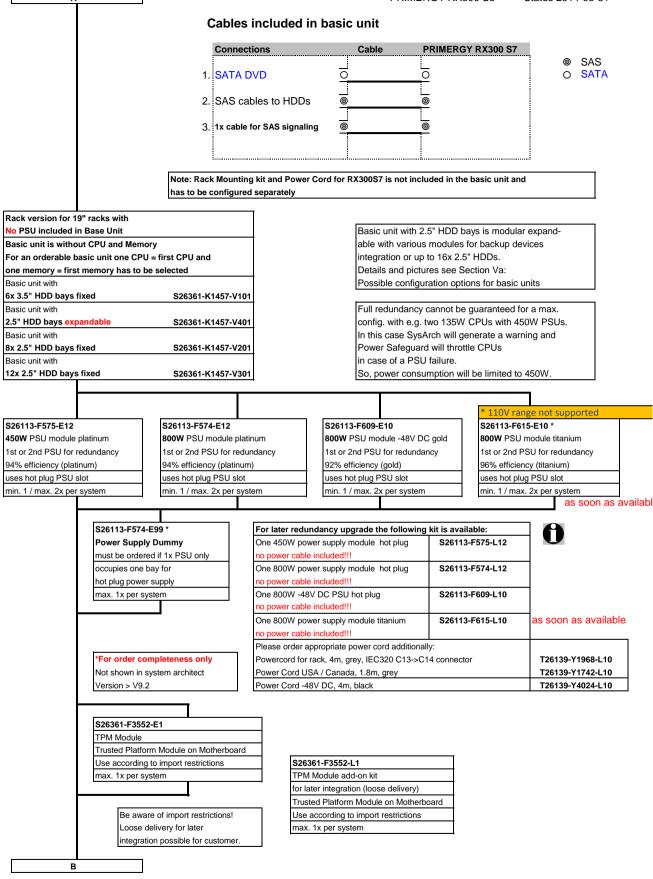


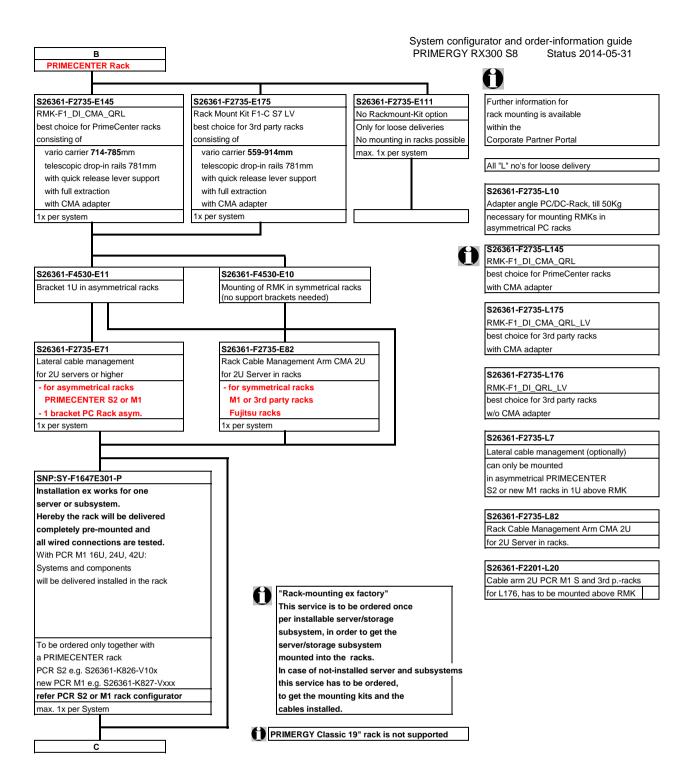


Start PRIMERGY RX300 S8

Start PRIMERGY RX300 S8	PRIMERGY RX300 S8	Status 2014-05-31
Section	Basic unit	
Section	Basic unit         stem unit consisting of:         U Housing without power supply modules         tasic units with:         2 Hot-Plug Power Supply Bays         5 Fans (full redundancy)         12 memory DIMMs per CPU (max 768GB) => Total 24 DIMMs (max 1536GB) for two CPU's         AS Backplane for 6x 3.5" HD, SAS Backplanes for 4, 8, 12 or 16x 2.5" HD or PCle Backplanes for         or 8 PCle SSD with cable connection to on-board, modular RAID Controller         vrives/Bays         - 6 bays 1" for hot plug 3.5" HD (1" high) or 4, 8, 12 or 16 bays for hot plug 2.5" HD         - 1 bay for 3.5" and 1.6" high Backup device, consumes 2 bays for 3.5" HD for basic unit 6x 3.5" HD         - 1 bay for 5.25" and 1.6" high Backup device, not possible for basic unit 6x 3.5" HD         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height (option)         - 1 bay for or DVD-ROM 0,5" height	Status 2014-05-31
	irst CPU has to be selected for an orderable basic unit,	
* 0	hipset Intel® C600 Series (codenamed Patsburg)	
* 7	PCI slots:       - 2x       PCIe-3 x16 (both slots are connected to CPU 2 and are useable with configure         - 4x       PCIe-3 x8 (one notched to install x16 cards)         - 1x       PCIe-3 x8 (for internal modular RAID controller only)	ed 2nd CPU only!)
-	4 memory slots for max. 1536GB RAM DDR3 available Memory is divided into 12 DIMMs per CPU ( 4 channels with 3 slots per channel ) Possible max. configurations are: 16x 8GB UDIMM (dual rank modules) = 128GB 24x 16GB RDIMM (dual rank modules) = 384GB 24x 32GB LRDIMM (quad rank modules) = 768GB 24x 44GB LRDIMM (eight rank modules) = 1536GB First Memory ( one module ) has to be selected for an orderable basic unit per CPU Memory upgrade is possible module wise Memory mirrroring is supported with 2 identical modules in channel A+B CPU 1 or D+E CPU 2 Hot Spare Memory is supported for memory modules,	2
* ii d T	Pual Port 10/100/1000 x4 PCI Express* Gigabit Ethernet Intel LAN controller Powerville on-board RMC S4 (integrated Remote Management Controller) on-board server management controller with edicated 10/100/1000 Service LAN-port and integrated graphics controller. he Service LAN-port can be switched alternatively on standard Gbit LAN port 1	
1	raphics Controller integrated in iRMC S4 (integrated Remote Management Controller): 500x1200x16bpp 60Hz, 1280x1024x16bpp 60Hz, 1024x768x32bpp 75Hz, 800x600x32bpp 85Hz, 40x480x32bpp 85Hz 280x1024x24bpp 60Hz only possible if local monitor or remote video redirection is off)	
* 1 * 1 * 4	erfaces at the rear: x RS-232-C (serial, 9 pins) (usable for BMC or OS or shared) x VGA (15 pins) x USB <b>2.0</b> ( UHCI ) with <b>480MBit/s,</b> no USB wakeup x LAN RJ45, 1x Service-LAN RJ45	
* 2 * 1	erfaces on the front: x USB <b>2.0</b> ( UHCI ) with <b>480MBit/s</b> , no USB wakeup x VGA (15 pins) as an option x Service-LAN RJ45 as an option	
* 1 * 1 * 1 * 4	erfaces internal: x released internal USB Interfaces for backup devices, x USB 2.0 (UHCI) with 480MBit/s for dongle funcionality (uSSD memory), no USB wakeup x SATA interface for DVD (only usable with 4x 2.5" HDD + DVD Option) x SATA/SAS interface for 4 SATA/SAS HD's or SAS Backup device x USB 2.0 ports for internal USB redirection connected to BMC	
* 5	ftware: erverView Suite Software package incl. ServerStart, ServerBooks, Management Software and Upd locumentation engl. (multilingual on CD)	ates

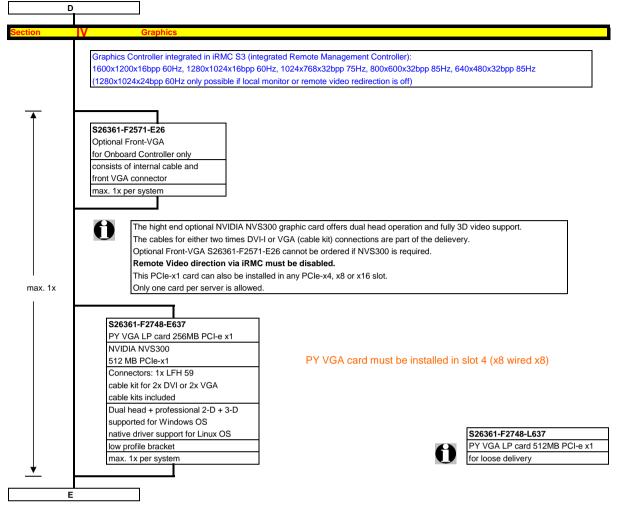
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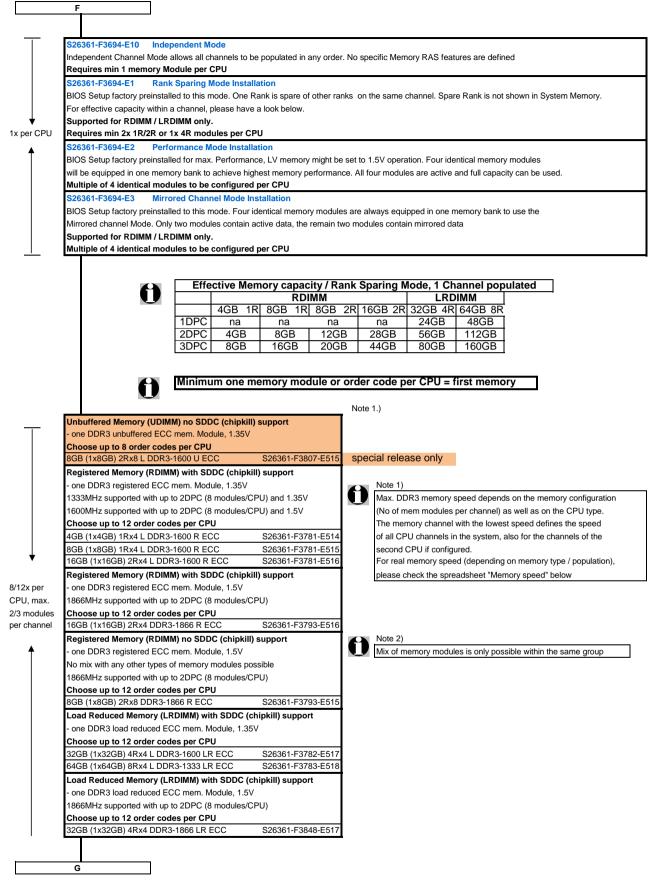


Section Processor		
There are 2 processor sockets available.		
The first socket must always be equipped with	h the first CPU which can be s	selected via configurator
It is also possible to upgrade a dual-processo		÷
Both PCIe-3 x16 slots are connected to CI	•	· · · · · · · · · · · · · · · · · · ·
Two processors with different clock frequ		
A multi-processor operating system is require	•	ı.
······································		
Max. two CPU`s can be selected per basic unit		
One of following CPU's has to be selected as first CPU		
for an orderable basic unit		
Optional second CPU has to be the same type like the first CPU		
Basic 4C CPU's		Max. DDR3 Bus Speed depends on:
- 1x 64-bit Intel Xeon (10MB Smart Cache)		- max. DDR3 Bus Speed depends on:
1333 MHz DDR3 Bus; 6,40 GT/s QPI Bus and passive heat sink		- max. DDR3 Memory Speed and
occupies socket for one CPU		- max. memory modules on one memory channel
Xeon E5-2603v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E180	For CPUs which do not offer 1866 MHz support,
Xeon E5-2609v2 4C/4T 2.50GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E250	(Basic, Standard & Low Power class),
Standard Turbo 6C/8C CPU's		System Architect will not offer memory modules
<ul> <li>1x 64-bit Intel Xeon (15/20MB Smart Cache); Hyper-Threading (HT);</li> <li>1600 MHz DDR3 Bus; 7,20 GT/s QPI Bus and passive heat sink</li> </ul>		supporting this frequency.
occupies socket for one CPU		
Xeon E5-2620v2 6C/12T 2.10GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E210	
Xeon E5-2630v2 6C/12T 2.60GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E260	
Xeon E5-2640v2 8C/16T 2.00GHz 20MB 7.20GT/s 1600MHz 95W	S26361-F3789-E200	
Advanced Turbo+ 8C/10C CPU`s		
- 1x 64-bit Intel Xeon (20/25MB Smart Cache); Hyper-Threading (HT);		
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2650v2 8C/16T 2.60GHz 20MB 8.00GT/s 1866MHz 95W	S26361-F3790-E260	
Xeon E5-2660v2 10C/20T 2.20GHz 25MB 8.00GT/s 1866MHz 95W	S26361-F3790-E220	
Xeon E5-2670v2 10C/20T 2.50GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E250	
Xeon E5-2680v2 10C/20T 2.80GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E280	
Xeon E5-2690v2 10C/20T 3.00GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3790-E300	
Segment Optimized CPU`s		
- 1x 64-bit Intel Xeon (15/25/30MB Smart Cache); Hyper-Threading (HT);		
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2637v2 4C/8T 3.50GHz 15MB 8.00GT/s 1866MHz 130W	S26361-F3791-E350	
Xeon E5-2643v2 6C/12T 3.50GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3791-E330	
Xeon E5-2667v2 8C/16T 3.30GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3791-E300	
Xeon E5-2695v2 12C/24T 2.40GHz 30MB 8.00GT/s 1866MHz 115W Xeon E5-2697v2 12C/24T 2.70GHz 30MB 8.00GT/s 1866MHz 130W	S26361-F3791-E240 S26361-F3791-E270	
Low Power 6C/10C CPU's	320301-1 3731*E270	
- 1x 64-bit Intel Xeon (15/25MB Smart Cache); Hyper-Threading (HT);		
1600 MHz DDR3 Bus; 7,20/8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2630Lv2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W	S26361-F3792-E240	
Xeon E5-2650Lv2 0C/20T 1.70GHz 25MB 7.20GT/s 1600MHz 70W	S26361-F3792-E170	

С



	-	PRIMERGY RX300 S8 Status 2014-05
	<u>Е</u>	
Section		Memory
		There are 12 memory close per CBU for mov
		- There are 12 memory slots per CPU for max. 768GB LRDIMM (12x 64GB 8R)
	•	192GB RDIMM (12x 16GB 2R)
		64GB UDIMM (8x 8GB) on special Release only
		=> max. 1.536GB for two CPU's (768GB per CPU), using LRDIMM
		- The memory area is divided into 4 channels per CPU with 3 slots per channel
		- Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2,
		slot 3 belongs to memory bank 3
		Registered, LR DIMMs and unbuffered memory modules can be selected
		No mix of registered, load reduced and unbuffered modules allowed.
		Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.
		Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).
		In a single DIMM per channel configuration, following frequencies are supported:
		- 1.5V - 1866MHz max (depending on CPU)
		- 1.35V - 1600MHz max (depending on CPU, up to two LRDIMM per channel)
		- 1.35V - 1333MHz max (up to two UDIMM or RDIMM per channel)
		In a 3 DIMMs per channel configuration, memory will operate at 1.35V or 1.5V (no UDIMM allowed).
		SSD (Chipkill) is supported for registered / load reduced x4 organized memory modules only.
		1.) In the "Independent Channel Mode" is following configuration possible
		Channels can be populated in any order in Independent Channel Mode. All four
		channels may be populated in any order and have no matching requirements. All
		channels must run at the same interface frequency but individual channels may run at
		different DIMM timings (RAS latency, CAS latency, and so forth)
		No mix of registered, load reduced and unbuffered modules allowed.
		2.) "Rank Sparing Mode" configuration
		- Within a memory channel, one rank is a spare of the other ranks.
		The Spare Rank is held in reserve and is not available as system memory
		For the effective memory capacity, please refer to the spreadsheet below.
		The BIOS is set to the rank sparing setting. Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel
		This mode is not supported by unbuffered memory modules
		3.) "Performance Mode" configuration
		- In this configuration, the memory module population ex factory is spread across all channels.
		The BIOS is set to the max. performance for memory.
		Minimum configuration is: 4x identical modules
		4.) In the "Mirrored Channel Mode" is following configuration possible
		- Each memory bank can optionally be equipped with 4x registered or load reduced or unbuffered DDR3 modules
		In each memory bank channel A and B / C and D of CPU 1 or channel E and F / G and H of CPU 2 have to be
		equipped with identical modules for mirrored channel mode.
		In channel B / D is always the mirrored memory of channel A / B of CPU 1
		In channel F / H is always the mirrored memory of channel E / G of CPU 2
		Minimum configuration is: 4x identical modules
		This mode is not supported by unbuffered memory modules
	F	



#### Memory Configuration PRIMERGY RX300 S8

Each CPU offers 12 **Slots** for DDR3 Memory Modules organised in **3 Banks and 4 Channels.** If you need more than 12 Slots you have to configure the 2nd CPU. Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application
		ODIMIN	RDIWIW	LRDIMM	
		x8	x8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

\*) For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x4GB	1x4GB	1x32GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x64GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	1536GB	if second CPU is configured

#### Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
	UDIMM 1866MHz		RDIMM 1866MHz					LRDIMM 4R 1866MHz										
Voltage setting (BIOS)	1.5V [default]		1.5V [default] 1.35V			1.5V [default] 1.35V			1.5V [default] 1			1.35\	/					
	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1866MHz DDR3 Bus	1866	1600	-	1333	1333		1866	1866	1066	1333	1333	800	1866	1866	1066	1600	1600	1066
CPU with 1600MHz DDR3 Bus	1600	1600	-	1333	1333	-	1600	1600	1066	1333	1333	800	1600	1600	1066	1600	1600	1066
CPU with 1333MHz DDR3 Bus	1333	1333	-	1333	1333	-	1333	1333	1066	1333	1333	800	1333	1333	1066	1333	1333	1066

1R - Single Rank4R - Quad Rank2R - Dual Rank8R - Eight Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel 3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

Bank I black sockets

Bank II blue sockets Bank III green sockets

Sank III green sockets

Bank I on CPU 1/2 up to 4 me Bank II on CPU 1/2 up to 4 me Bank III on CPU 1/2 up to 4 me

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below) Bank I on CPU 1/2 up to 4 memory modules connected to Channel A - H on the 1st/2nd CPU

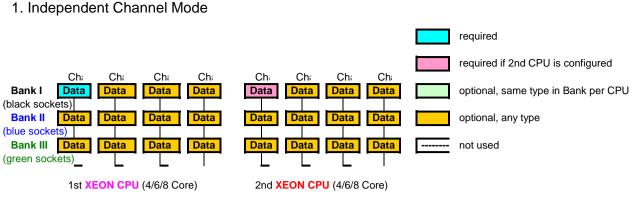
up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU

up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU

(can not be populated by UDIMM or 4R RDIMM memory modules)

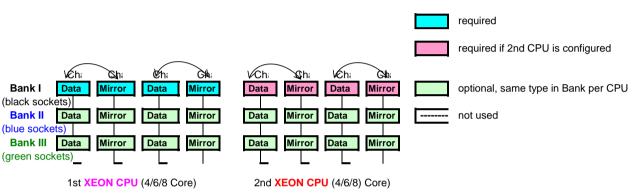
- See below and next page for a detailed descriptions of the memory configuration supported.

System configurator and order-information guide PRIMERGY RX300 S8 Status 2014-05-31



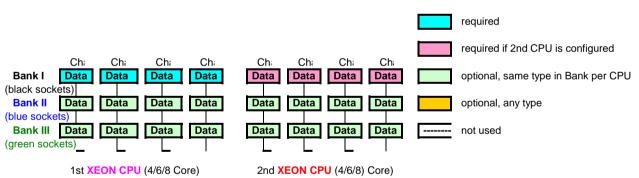
Independent Channel Mode allows all channels to be populated in any order Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

#### 2. Mirrored Channel Mode



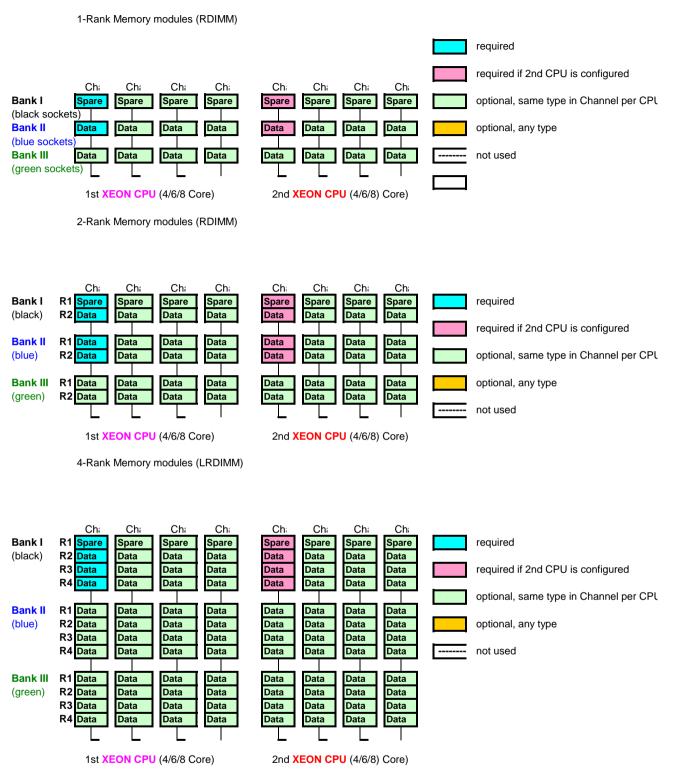
Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 4 identical modules has to be ordered.

#### 3. Performance Channel Mode



Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 4 identical modules has to be ordered.

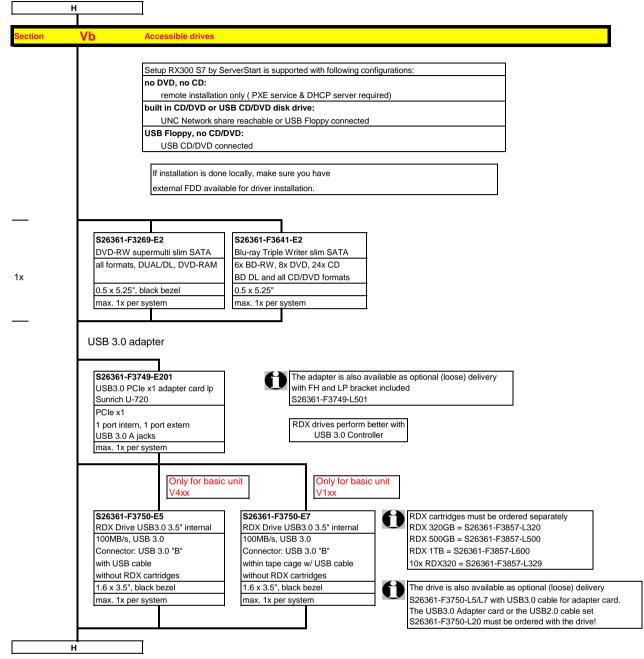
#### 4. Rank Sparing Mode

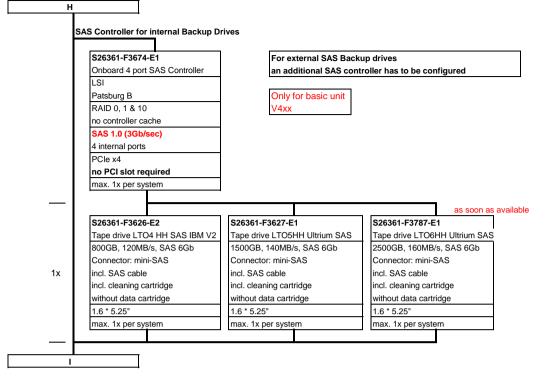


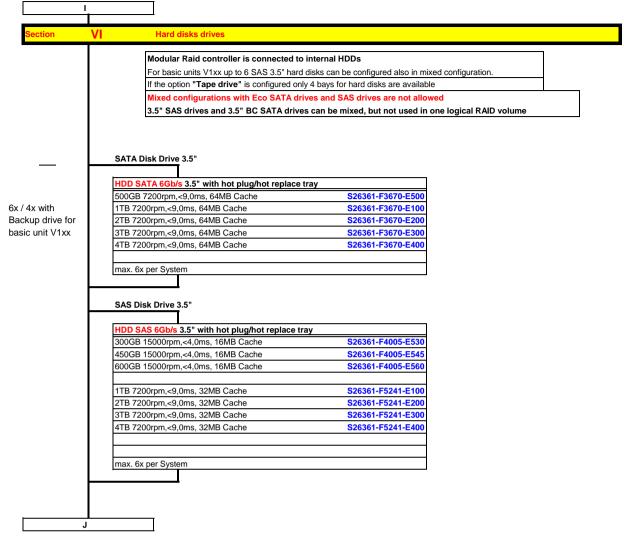
Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

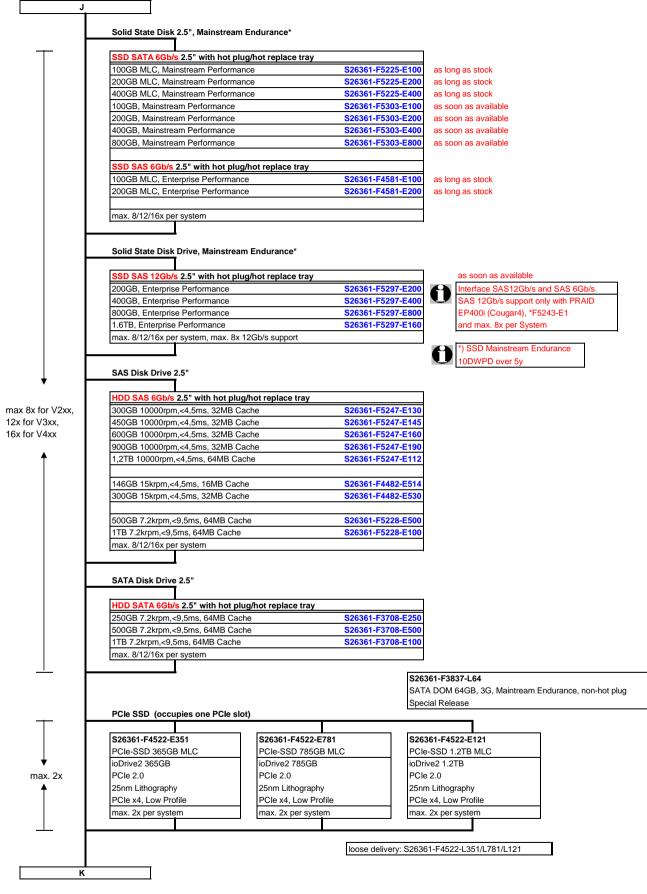
	Is fixed due to selection of basic unit with: 6x 3,5" HDD bays fixed	S26361-K1457-V10
	These options are available in Q2/2014	no PCle SSD SF
	Basic unit S26361-K1457-V401 with	expandable
the second second	Config 2: 4x 2.5" HDD	S26361-F1373-E420
	Available Upgrade kits for this configuration	n option:
	Upgrade kit to 8x 2.5" HDD	S26361-F1373-L424
ALCONCEPTION OF	Upgrade kit to 12x 2.5" HDD	S26361-F1373-L427
	Upgrade kit to 4x 2.5" HDD + LTO	S26361-F1373-L423
	Upgrade kit to 4x + 8x 2.5" SAS3.0	S26361-F1373-L57
	Basic unit S26361-K1457-V401 with	expandabl
	Config 3: 4x 2.5" HDD + LTO	S26361-F1373-E430
The second se	Basic unit S26361-K1457-V401 with	expandabl
	Available Upgrade kits for this configuration	n option:
	Upgrade kit to 8x 2.5" HDD	S26361-F1373-L430
	Basic unit S26361-K1457-V201 with	
	Config. 4: 8x 2,5" HDD bays fixed	S26361-K1457-V20
and the second s	Available Upgrade kits for this fixed config	
PROPERTY AND A DESCRIPTION OF A DESCRIPT	Upgrade kit to 12x 2.5" HDD	S26361-F1373-L247
	Upgrade kit to 16x 2.5" HDD	S26361-F1373-L248
	Basic unit S26361-K1457-V401 with	expandable
	Config 5: 8x 2.5" HDD + 3.5" drive	S26361-F1373-E450
and the second s	Config 12: 3.5" drive + 8x SAS3.0	S26361-F1373-E550
	No Upgrade kit available!	
MARK IN THE REAL PROPERTY OF THE REAL PROPERTY	Basic unit S26361-K1457-V401 with	expandable
	Config 6: 8x 2.5" HDD + LTO	S26361-F1373-E460
the second se		
	Config 15: LTO + 8x SAS3.0 no ODD and LSD bay available!	S26361-F1373-E560
	No Upgrade kit available!	
A CONTRACT OF A	Pagia unit 000004 K4457 M004 with	
And the statement of the	Basic unit S26361-K1457-V301 with Config 7: 12x 2,5" HDD bays fixed	S26361-K1457-V30 <sup>2</sup>
A second se	Basic unit S26361-K1457-V401 with	expandable
	Config 10: 4x SAS2.0 + 8x SAS3.0	S26361-F1373-E572
	Available Upgrade kits for this configuration	ins:
The second s	Upgrade kit to 16x 2.5" HDD	S26361-F1373-L378
	Basic unit S26361-K1457-V401 with	expandable
and the second s	Config 8: 16x 2.5" HDD	S26361-F1373-E480
The second second second second	no ODD and LSD bay available!	
	No Upgrade kit available!	
	Includes all necessary bezels, cages, back	planes and cables

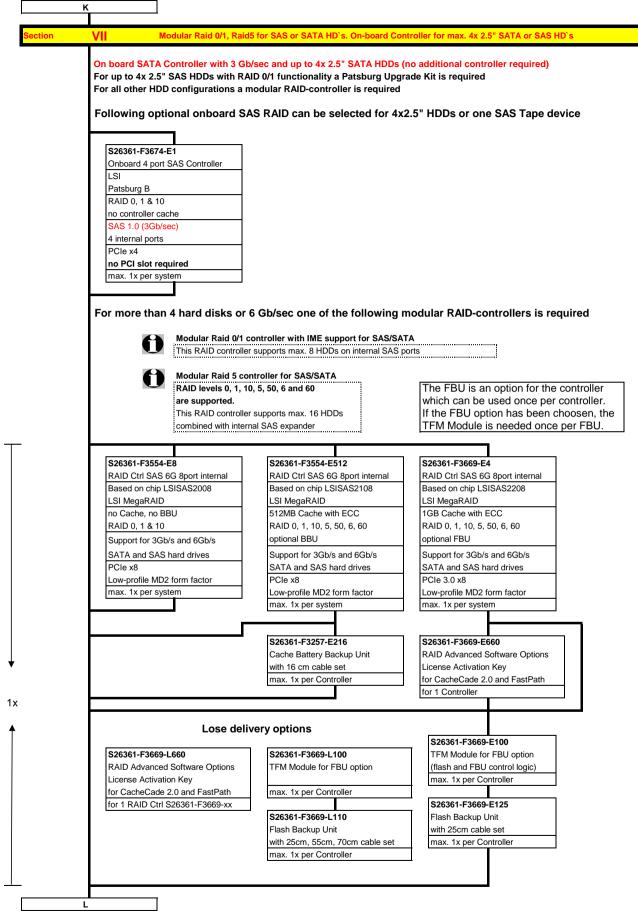
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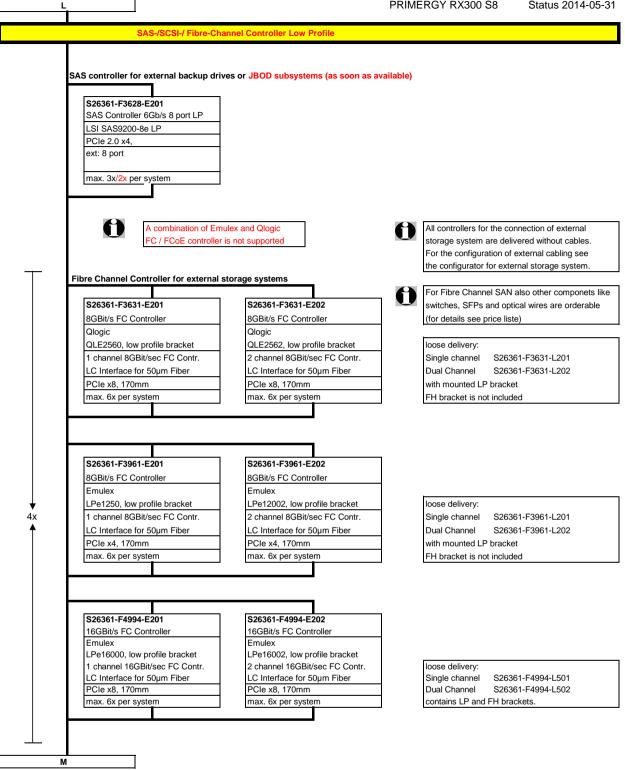


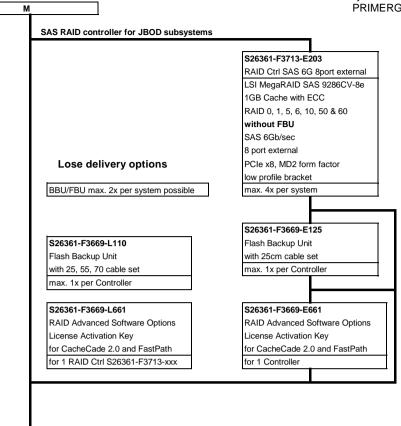




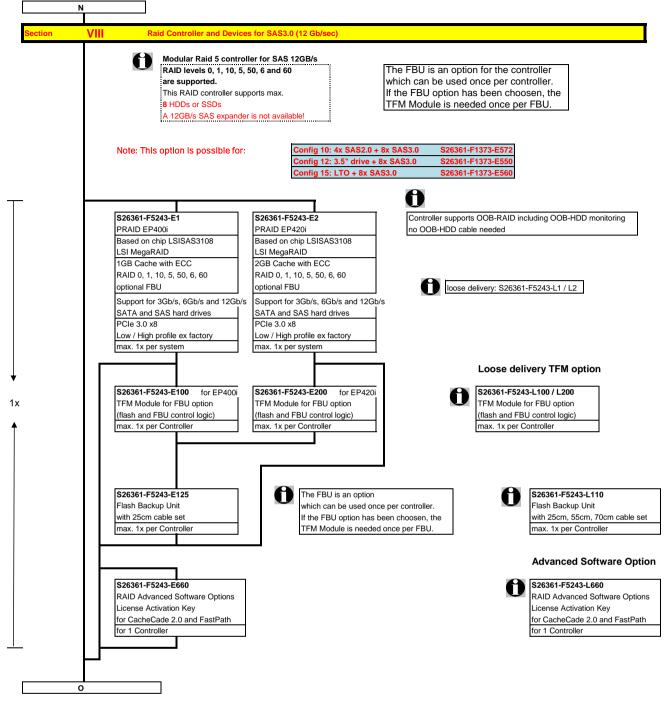


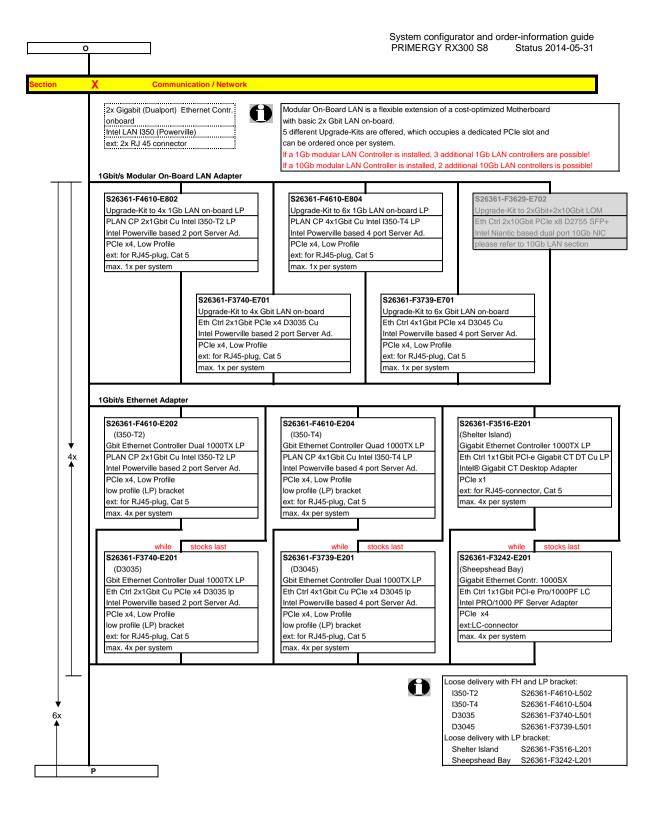


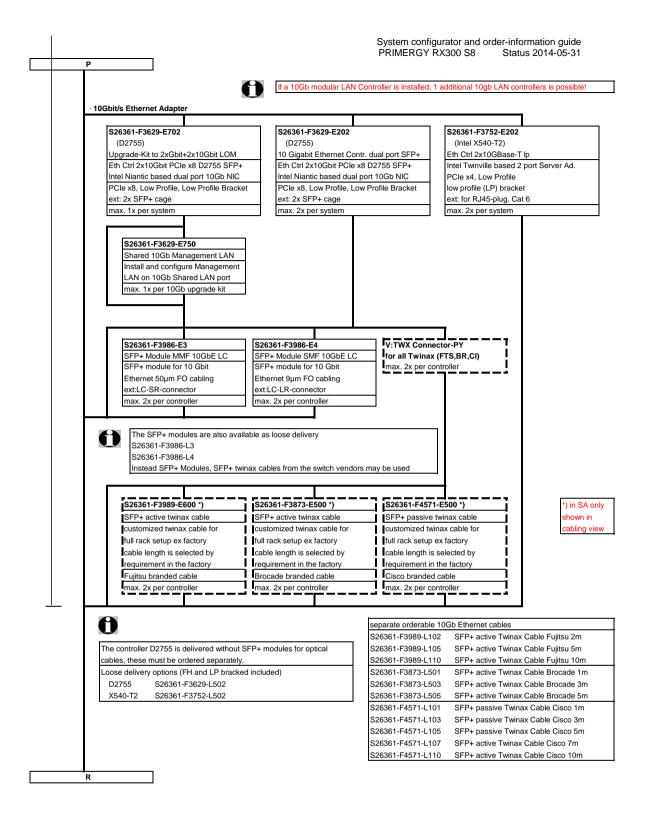


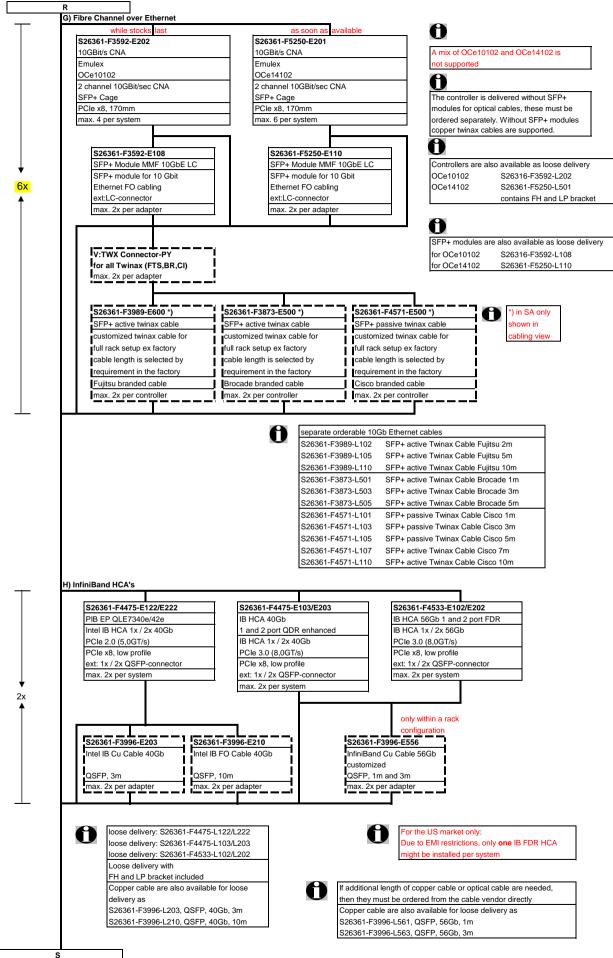


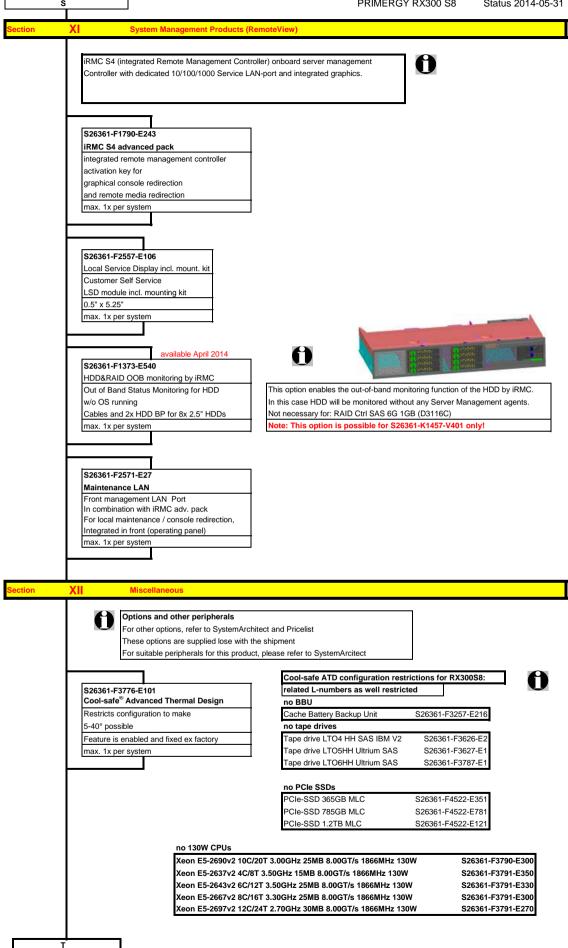
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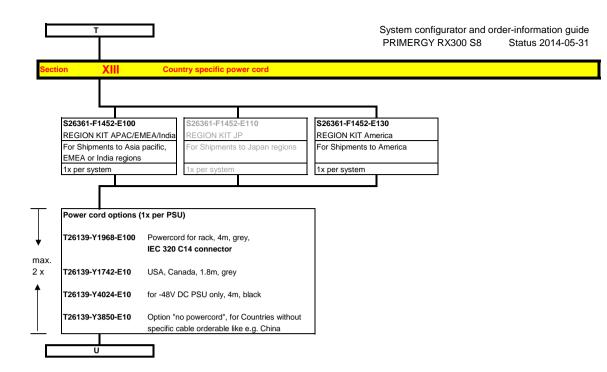












		PRIMERGY RX300 S8 Status 2014-
ion	XVI CCC exclusions	
	S26361-F3301-E120	
	CCC Certification for China	
	Limits configuration in accordance	
	with CCC exclusions	
	max. 1x per system	
	The following order components out of the spo are NOT allowed together with CCC Certification	
	are NOT allowed together with CCC Certification	on for China:
	5	
	Front-VGA Interface	S26361-F2571-E26
	PCIe-SSD 365GB MLC	S26361-F4522-E351
	PCIe-SSD 785GB MLC	S26361-F4522-E781
	PCIe-SSD 1.2TB MLC	S26361-F4522-E121
	SAS Ctrl 6G 8ext PCIe lp	S26361-F3628-E201
	Shared 10Gb Management LAN Kit	S26361-F3629-E750
		·
	Modulare SV 800W titanium hp	S26113-F615-E10
	Modulare SV DC -48V 800W gold hp	S26113-F609-E10
	Cable powercord rack, 4m, grey	T26139-Y1968-E100
	Ltg Netzanschluss -48V DC, 4m, schwarz	T26139-Y4024-E10
	Leitung Netzanschluss (USA), 1,8m, grau	T26139-Y1742-E10
	TPM Modul	S26361-F3552-E1

End PRIMERGY RX300 S8

#### **Change Report**

Date	Order number	Changes
2014-05-19	S26361-F3848-E517	Added 32 GB LRDIMM 1866 MHz
2014-05-06	S26361-F53250	new CNA OCe14102 added
2014-05-02		PCIe SSD SFF options removed
2014-04-03	S26361-F3776-E101	Cool-safe ATD restriction changed - 32GB and 64GB LRDIMM no more restricted
2014-03-18		SAS3.0 RAID Ctrl updated
2014-03-17	S26361-F3739-E201	phase out
2014-03-17	S26361-F3740-E201	phase out
2014-03-17	S26361-F3610-E202	EOL
2014-03-05	S26361-F1373-E540	HDD&RAID OOB monitoring by iRMC added
2014-01-30	S26361-F5303-*	New SATA SSDs added.
2014-01-30	S26361-F5297-*	New SAS 12G SSDs added.
2013-12-12	S26361-F3554-E8	restricted for ATD
2013-11-29	S26361-F3837-L64	SATA DOM (Disk on module) added
2013-11-27	S26361-F3301-E120	Restrictions CCC Certification for China updated
2013-10-28		SSD support with On-Board controller.
2013-10-28		restriction for 2.5" BC-SAS HDD with "*F3554-E8" removed.
2013-10-18	optional USB Comps	no longer available
2013-10-16	S26361-F4610-E202 / -E204	added new 1Gb NICs from Intel
2013-10-09	S26113-F615-E10	add comment "110V range not supported"
2013-10-08		restrictions for Cool-safe ATD added
2013-09-19		Memory hint on CPU page extended
2013-09-13	S26361-F5247-E112	HDD 1.2TB SAS 10K added.
2013-09-03	RMK	CMA not longer a must component
2013-09-01		First Release
	-	